



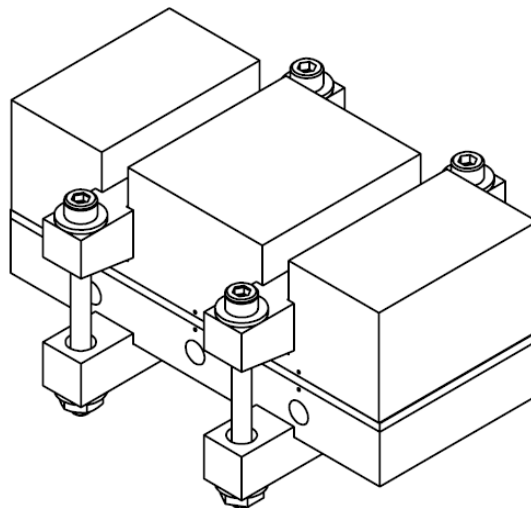
## Tflex B200MFG Thermal Reliability Report

### Summary

The Laird Technologies' gap filler reliability test procedure has been designed to characterize the long-term performance of a gap pad while being subjected to isothermal conditions, repeated extremes in temperature, and moderate heat - high humidity environments. Specimens are placed within application-related fixtures under set conditions and at regular intervals the thermal properties of the specimens are measured.

### Fixture Setup

The test fixture is rectangular with dimensions of 2" x 5" (surface area of 10 in<sup>2</sup>). It consists of an aluminum heater plate and an extruded aluminum heat sink "cooler plate". The heater plate contains 3 holes for insertion of cartridge heaters. Both plates contain 3 sets of thermocouple holes drilled for measurement of the temperature very near the surfaces mated by the gap pad. Each test fixture accommodates 3 test positions. The heater and cooler plates are held together by metal straps which span the width of the plates (2 sets per test fixture) and are bolted to each other. Cartridge heaters are inserted into the heater plate holes. A specified power from a power supply is input to the heaters to obtain a constant 70°C across the heater plate. This will ensure a constant heat flow is maintained through the gap filler during data acquisition. A cooling fan (not pictured) is centered on top of the heat sink during testing to facilitate realistic air flow and cooling. Test values are measured in an ambient laboratory environment.





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### Theory

Throughout the test period, the measured variable is the temperature difference of the surfaces of the heater and cooler plates. Thermal resistance ( $R_{th}$ ) is defined as the temperature difference ( $\Delta T$ ) between two surfaces for a given heat flow ( $\Delta P$ ). That is:  $R_{th} = \Delta T / \Delta P$ . In this testing, heat flow is controlled and constant, therefore,  $R_{th} \propto \Delta T$ . This relationship indicates that a constant value of  $\Delta T$  throughout the test program requires  $R_{th}$  to also remain constant, which indicates a highly reliable system and thus a gap pad that is not influenced by the test conditions.

### Types of Reliability Testing

#### Thermal Shock

In thermal shock testing, the test fixtures containing the specimens are transitioned between  $-50^{\circ}\text{C}$  and  $160^{\circ}\text{C}$  with a 1 hour hold to reach thermal equilibrium at each temperature extreme. The transfer time between the oven temperatures is quick, typically less than 20 seconds. 1000 cycles "Shocks" are performed on each fixture.

#### Isothermal Bake

In isothermal bake testing, fixtures are maintained at  $160^{\circ}\text{C}$  for 1000 hours.

#### HAST

In HAST testing, the fixtures are maintained in conditions of moderate temperature ( $85^{\circ}\text{C}$ ) and high humidity (85%) for the duration of the test.

### Results

The thicknesses of Tflex B200MFG tested were 40mil (1.016mm), 60mil (1.524mm) and 200mil (5.08mm). Two fixtures for each thickness were assembled and tested for all three reliability testing types (3 test positions for each unit). The data reported is the average of each value for the two fixtures.

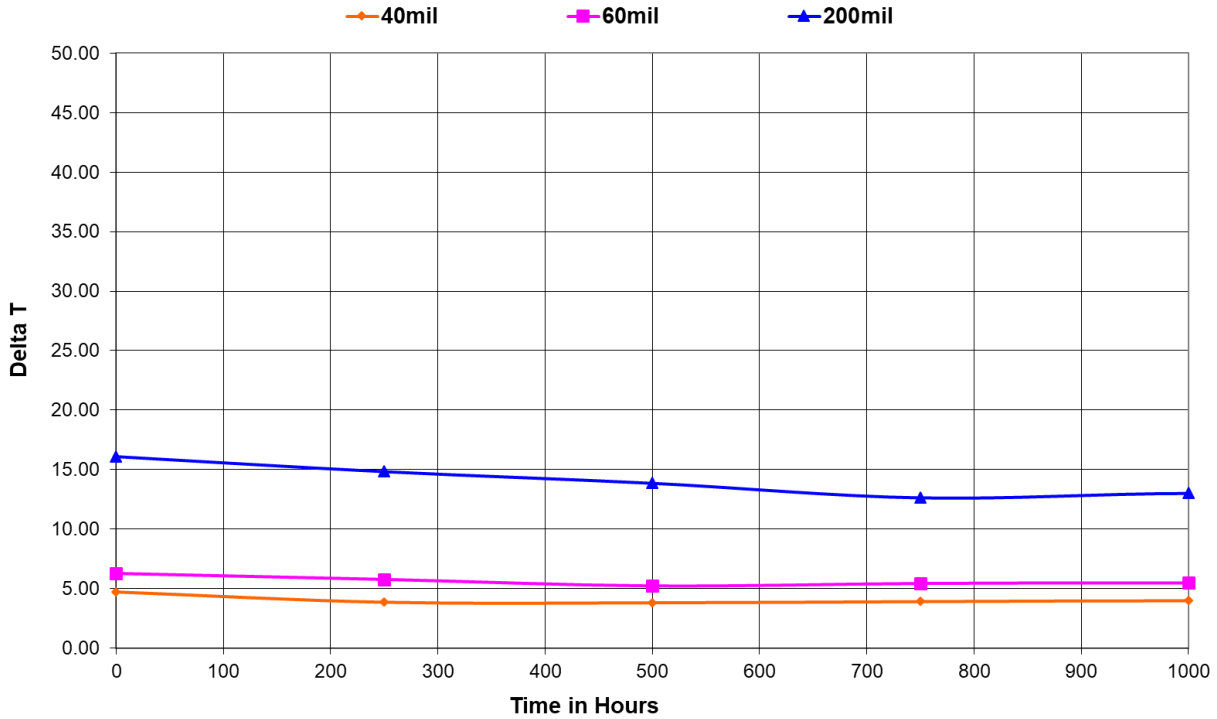
The change in temperature ( $\Delta T$ ) vs. time / # of cycles tested is reported below:



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## Thermal Shock

Tflex B200MFG Delta Temperature over 1000 cycles of -50°C to 160°C



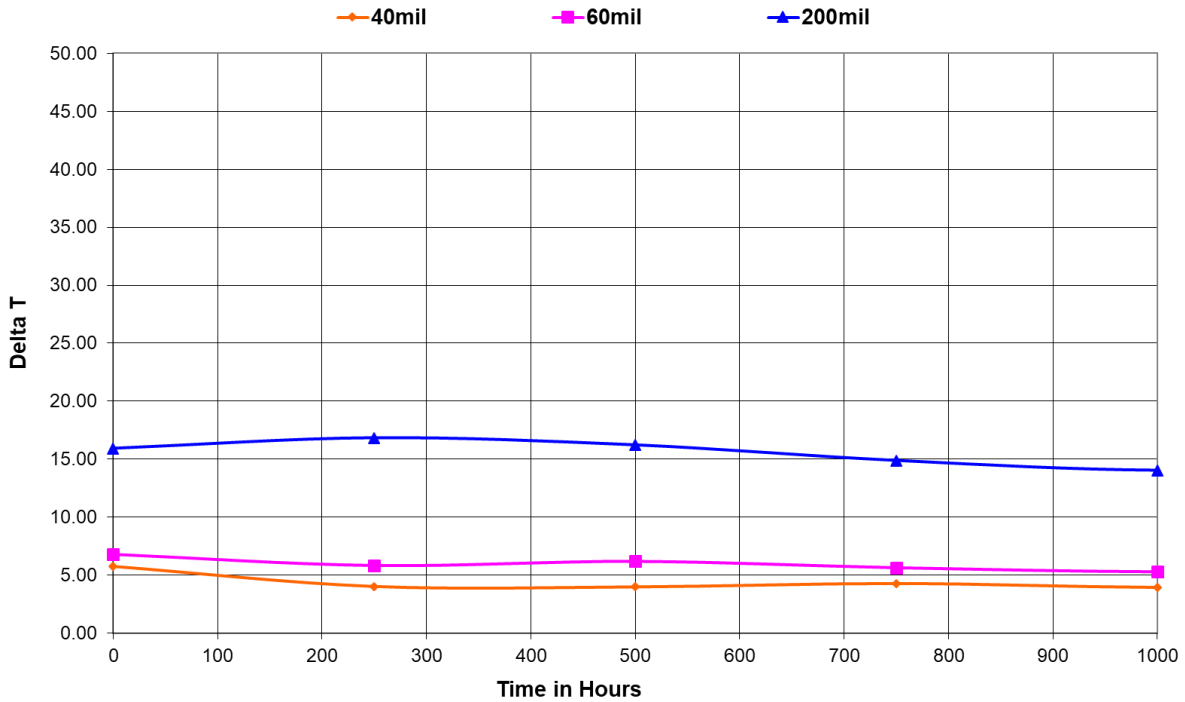
Material	Cycles	Avg $\Delta T$
<b>Tflex B240MFG</b>	0	4.73
	250	3.87
	500	3.83
	750	3.93
	1000	4.00
<b>Tflex B260MFG</b>	0	6.28
	250	5.78
	500	5.23
	750	5.44
	1000	5.48
<b>Tflex B2200MFG</b>	0	16.12
	250	14.85
	500	13.87
	750	12.64
	1000	13.02



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## Isothermal Bake

Tflex B200MFG Delta Temperature over 1000 hours at 160°C



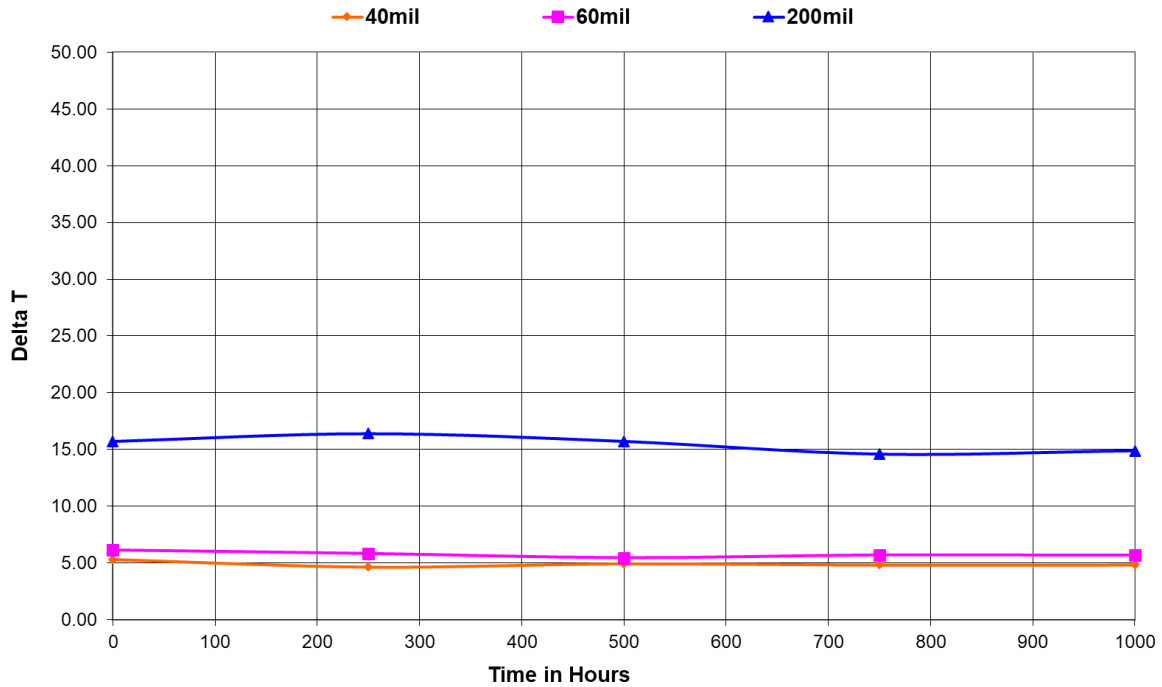
Material	Cycles	Avg $\Delta T$
<b>Tflex B240MFG</b>	0	5.75
	250	4.02
	500	3.98
	750	4.27
	1000	3.94
<b>Tflex B260MFG</b>	0	6.79
	250	5.83
	500	6.18
	750	5.64
	1000	5.29
<b>Tflex B2200MFG</b>	0	15.93
	250	16.83
	500	16.22
	750	14.88
	1000	14.04



# Tflex B200MFG Thermal Reliability Report

## HAST

Tflex B200MFG Delta Temperature over 1000 hours at 85% humidity and 85°C



Material	Cycles	Avg $\Delta T$
<b>Tflex B240MTG</b>	0	5.31
	250	4.64
	500	4.93
	750	4.82
	1000	4.83
<b>Tflex B260MTG</b>	0	6.13
	250	5.83
	500	5.45
	750	5.70
	1000	5.69
<b>Tflex B2200MTG</b>	0	15.71
	250	16.39
	500	15.72
	750	14.59
	1000	14.89



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### Conclusion:

As the graphs and data show, Tflex B200MFG performed consistently throughout the reliability testing program. No thermal degradation was evidenced for Tflex B200MFG under conditions of constant elevated temperature, thermal cycling, or a combination of moderate heat and high humidity. Therefore, it is shown that Tflex B200MFG will continue to perform as designed in long term applications under harsh environmental conditions such as these.

<b>Rev</b> 版本	<b>Summary of Change</b> 變更內容	<b>Author</b> 作者	<b>Approval Date</b> 審核日期
A	New release	Andy Zhao	5/17/2019